



SANYO Semiconductors

DATA SHEET

2SA2040/2SC5707 — PNP/NPN Epitaxial Planar Silicon Transistor

High-Current Switching Applications

Applications

- DC / DC converter, relay drivers, lamp drivers, motor drivers, flash

Features

- Adoption of FBET and MBIT processes
- Large current capacitance
- Low collector-to-emitter saturation voltage
- High-speed switching
- High allowable power dissipation

Specifications () : 2SA2040

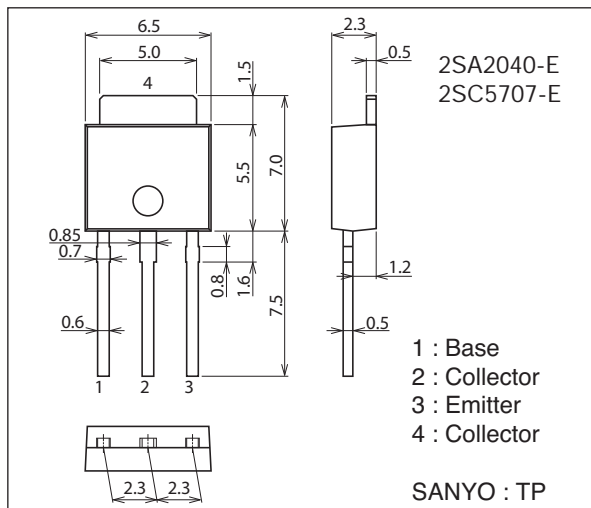
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	V _{CB0}		(-50)100	V
Collector-to-Emitter Voltage	V _{CES}		(-50)100	V
Collector-to-Emitter Voltage	V _{CEO}		(-50)	V
Emitter-to-Base Voltage	V _{EBO}		(-6)	V
Collector Current	I _C		(-8)	A
Collector Current (Pulse)	I _{CP}		(-11)	A

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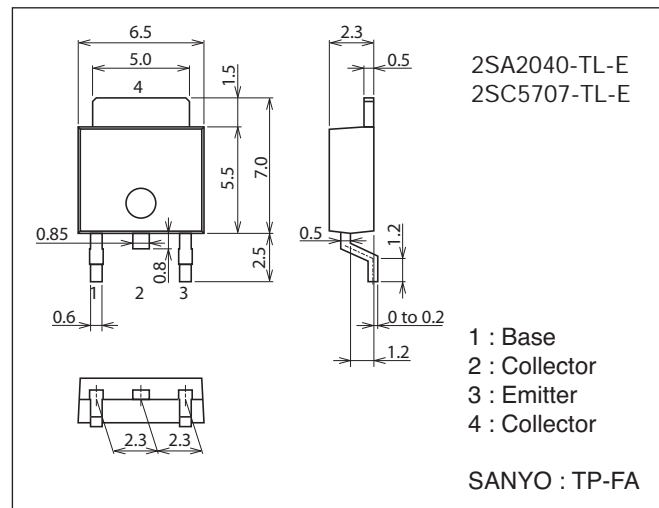
Package Dimensions unit : mm (typ)

7518-003



Package Dimensions unit : mm (typ)

7003-003

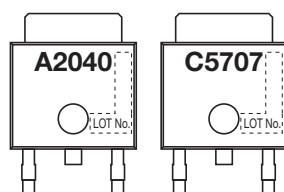


Product & Package Information

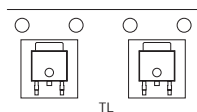
- Package : TP
- JEITA, JEDEC : SC-64, TO-251
- Minimum Packing Quantity : 500 pcs./bag

- Package : TP-FA
- JEITA, JEDEC : SC-63, TO-252
- Minimum Packing Quantity : 700 pcs./reel

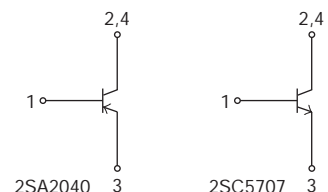
Marking (TP, TP-FA)



Packing Type (TP-FA) : TL



Electrical Connection



2SA2040/2SC5707

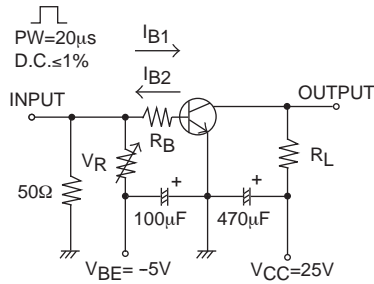
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Parameter	Symbol	Conditions	Ratings	Unit
Base Current	I_B		(-) 2	A
Collector Dissipation	P_C		1.0	W
		$T_C=25^\circ\text{C}$	15	W
Junction Temperature	T_j		150	$^\circ\text{C}$
Storage Temperature	T_{stg}		-55 to $+150$	$^\circ\text{C}$

Electrical Characteristics at $T_a=25^\circ\text{C}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Collector Cutoff Current	I_{CBO}	$V_{CB}=(-)40\text{V}, I_E=0\text{A}$			$(-)0.1$	μA
Emitter Cutoff Current	I_{EBO}	$V_{EB}=(-)4\text{V}, I_C=0\text{A}$			$(-)0.1$	μA
DC Current Gain	h_{FE}	$V_{CE}=(-)2\text{V}, I_C=(-)500\text{mA}$	200		560	
Gain-Bandwidth Product	f_T	$V_{CE}=(-)10\text{V}, I_C=(-)500\text{mA}$		$(290)330$		MHz
Output Capacitance	C_{ob}	$V_{CB}=(-)10\text{V}, f=1\text{MHz}$		$(50)28$		pF
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)1}$	$I_C=(-)3.5\text{A}, I_B=(-)175\text{mA}$		$(-230)160$	$(-390)240$	mV
	$V_{CE(sat)2}$	$I_C=(-)2\text{A}, I_B=(-)40\text{mA}$		$(-240)110$	$(-400)170$	mV
Base-to-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=(-)2\text{A}, I_B=(-)40\text{mA}$		$(-)0.83$	$(-)1.2$	V
Collector-to-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C=(-)10\mu\text{A}, I_E=0\text{A}$	$(-50)100$			V
Collector-to-Emitter Breakdown Voltage	$V_{(BR)CES}$	$I_C=(-)100\mu\text{A}, R_{BE}=0\Omega$	$(-50)100$			V
Collector-to-Base Breakdown Voltage	$V_{(BR)CEO}$	$I_C=(-)1\text{mA}, R_{BE}=\infty$	$(-)50$			V
Emitter-to-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E=(-)10\mu\text{A}, I_C=0\text{A}$	$(-)6$			V
Turn-On Time	t_{on}			$(40)30$		ns
Storage Time	t_{stg}	See specified Test Circuit.		$(225)420$		ns
Fall Time	t_f			25		ns

Switching Time Test Circuit

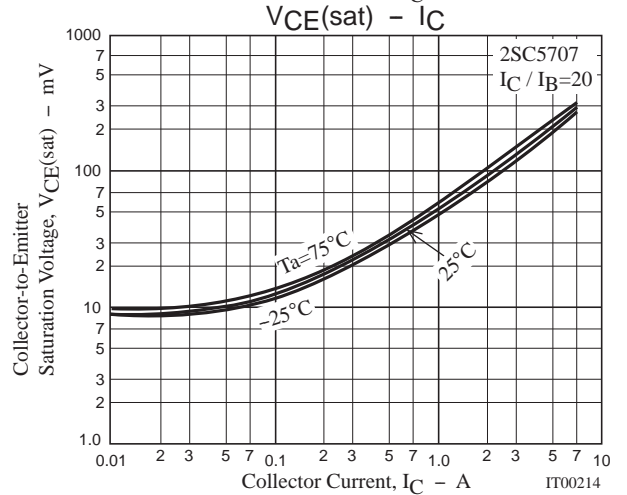
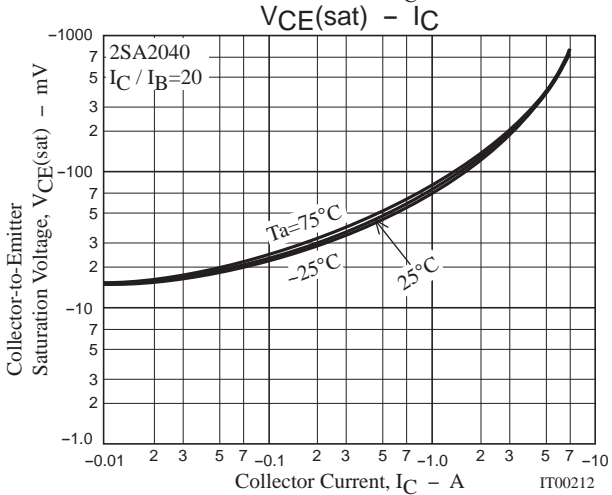
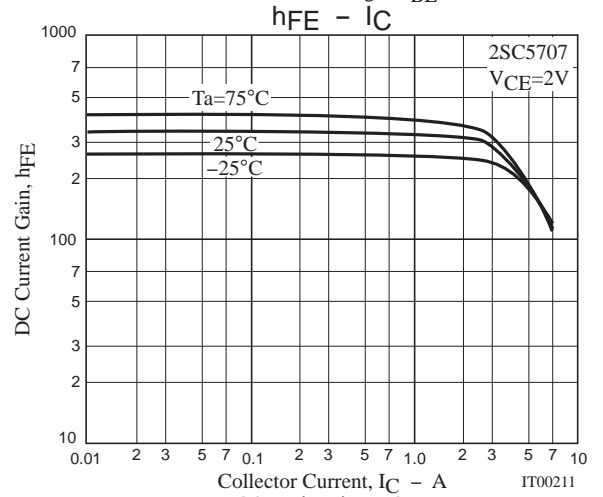
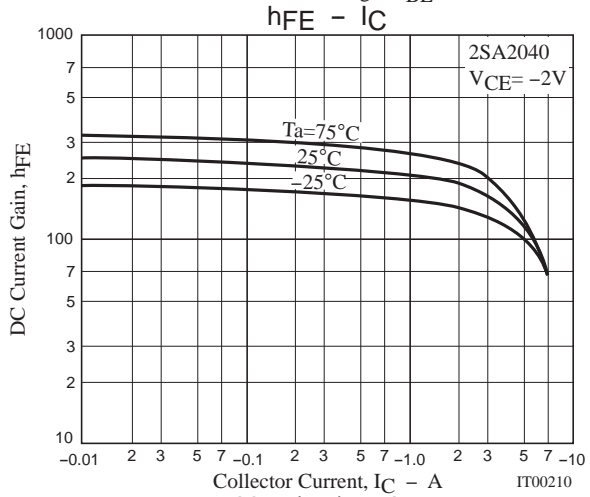
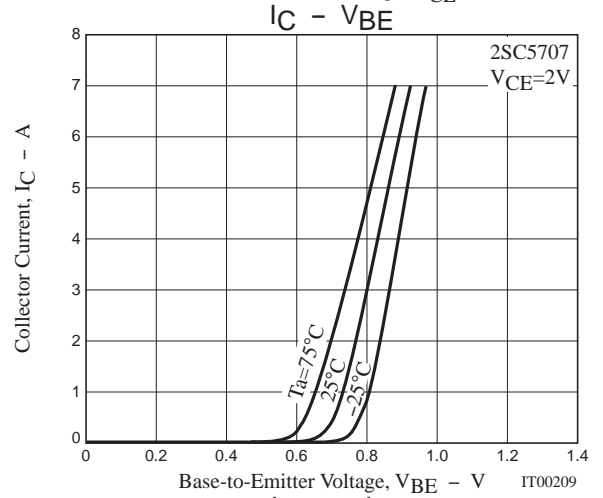
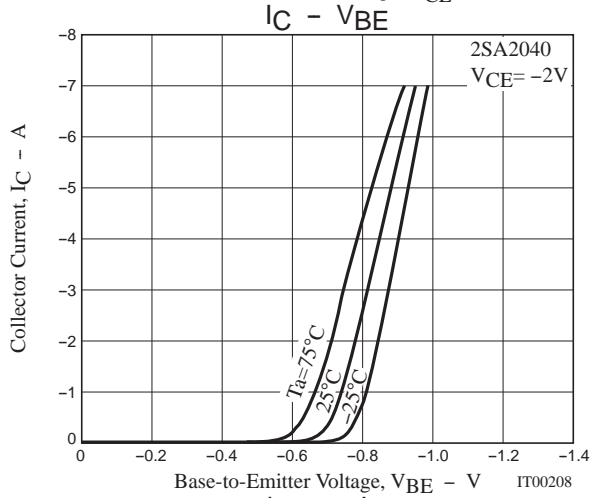
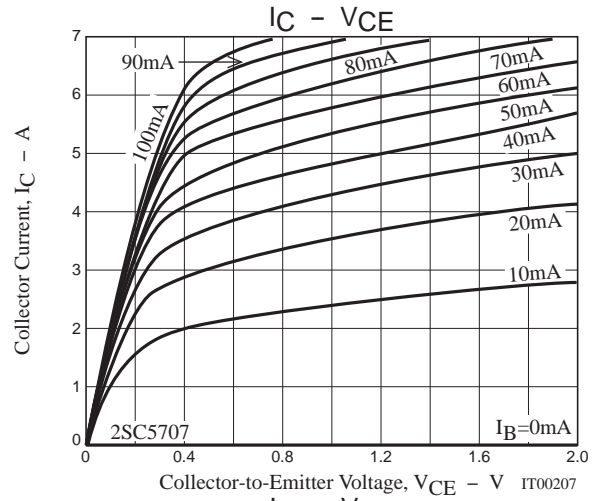
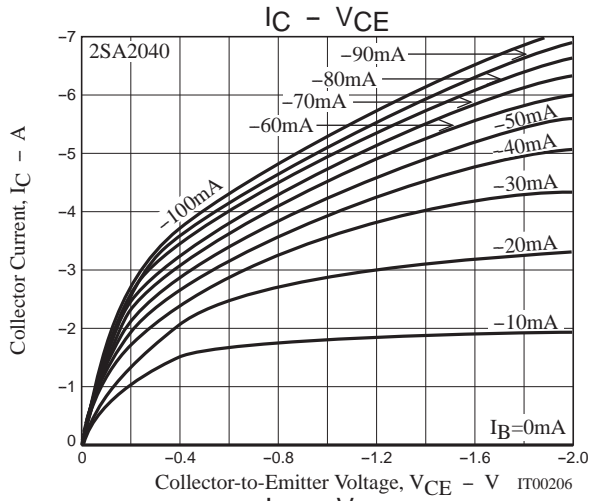


$$20I_{B1} = -20I_{B2} = I_C = 2.5\text{A}$$

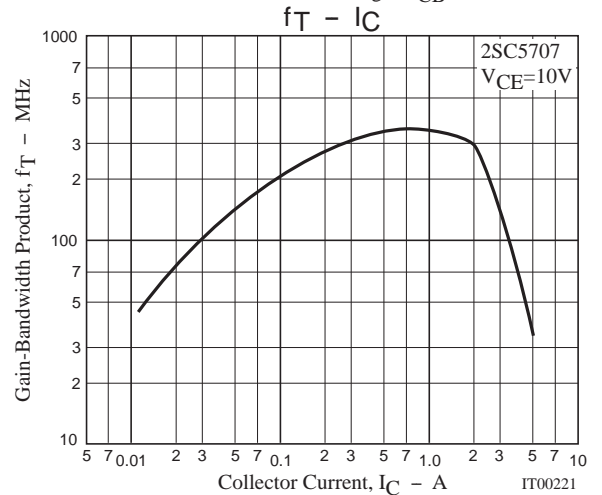
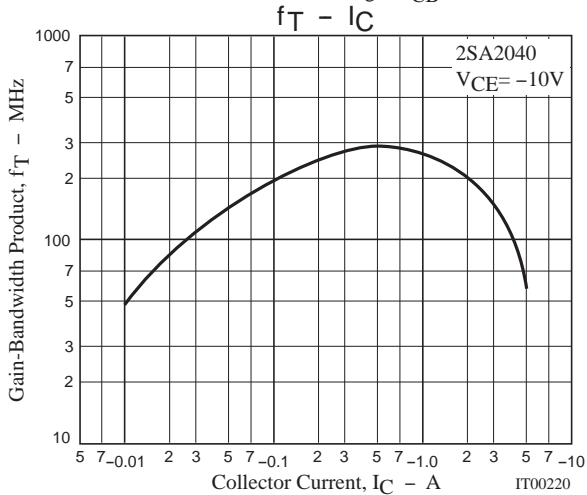
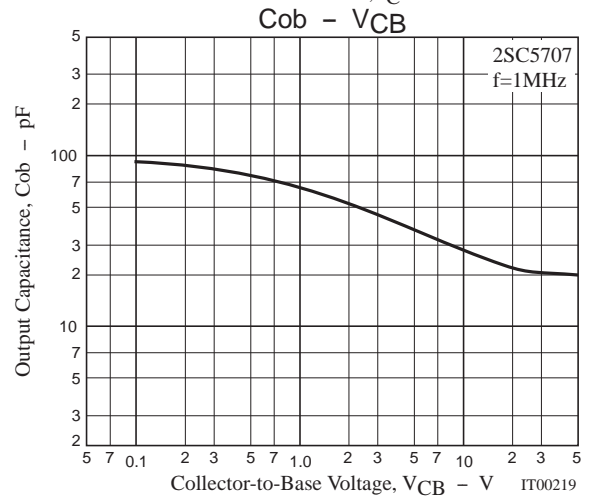
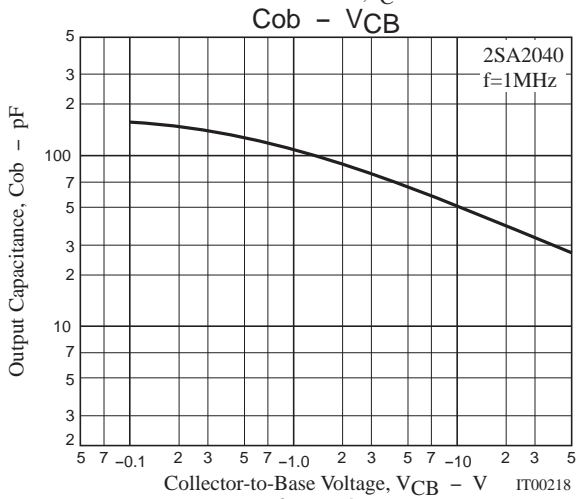
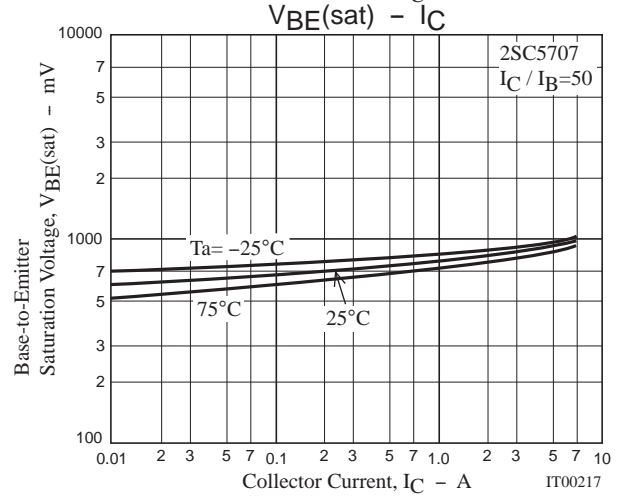
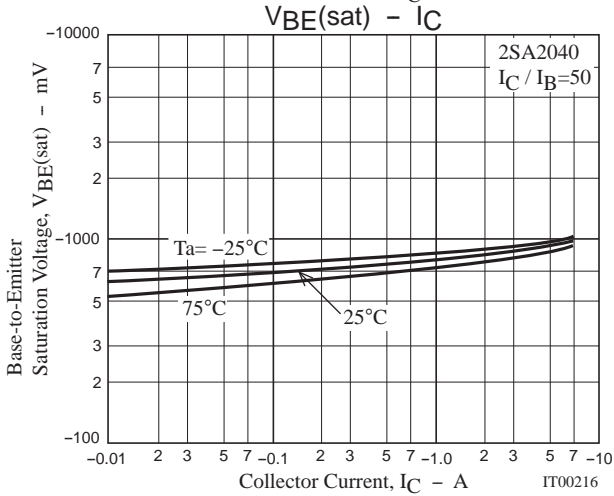
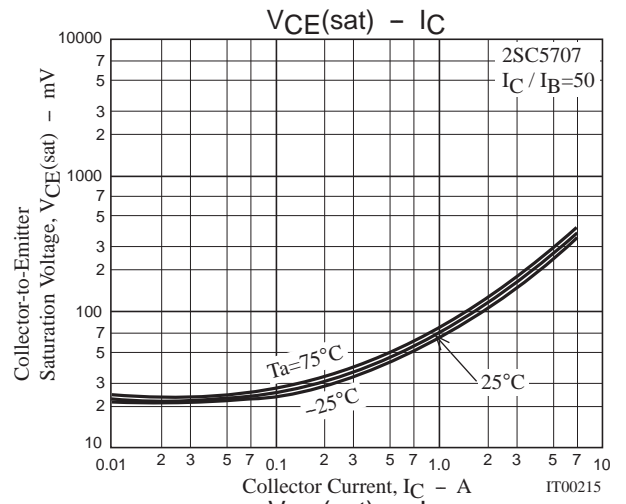
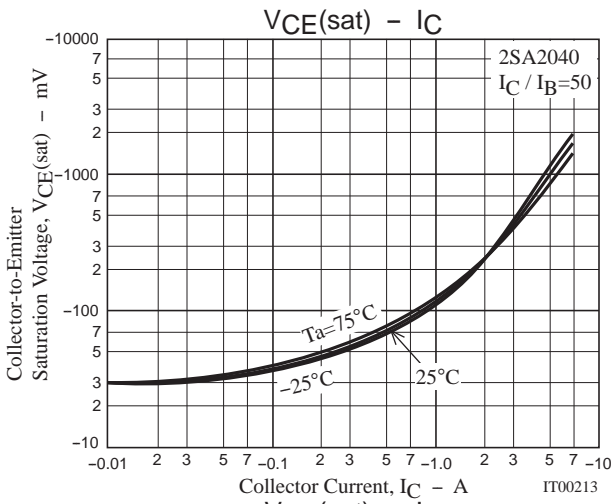
For PNP, the polarity is reversed.

Ordering Information

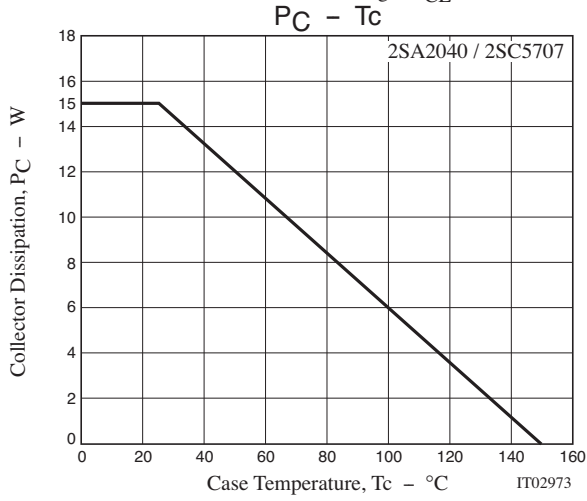
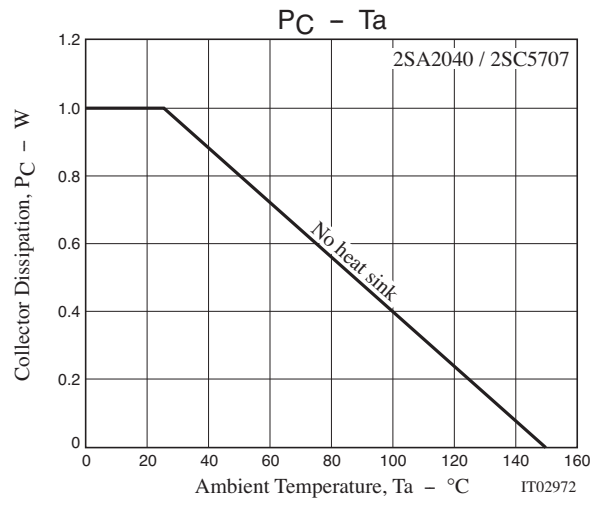
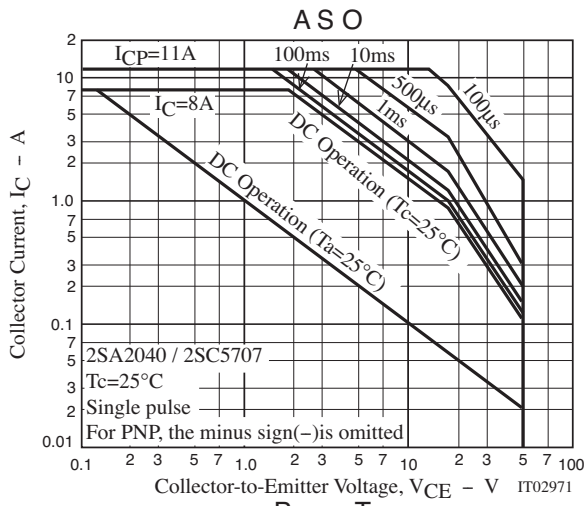
Device	Package	Shipping	memo
2SA2040-E	TP	500pcs./bag	Pb Free
2SC5707-E	TP	500pcs./bag	
2SA2040-TL-E	TP-FA	700pcs./reel	
2SC5707-TL-E	TP-FA	700pcs./reel	



2SA2040/2SC5707



2SA2040/2SC5707



Taping Specification

2SA2040-TL-E, 2SC5707-TL-E

Packing Format

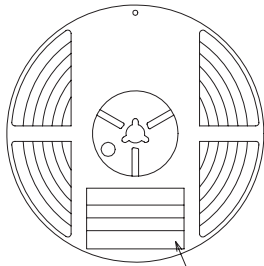
Package Name	Carrier Tape Type	Maximum Number of devices contained (pcs)			Packing format	
		Reel	Inner box	Outer box	Inner BOX (C-1)	Outer BOX (A-7)
TP-FA	TP	700	2,100	12,600	3 reels contained Dimensions:mm (external) 183×72×185	6 inner boxes contained Dimensions:mm (external) 440×195×210

Reel label, Inner box label
(unit:mm)

Outer box label

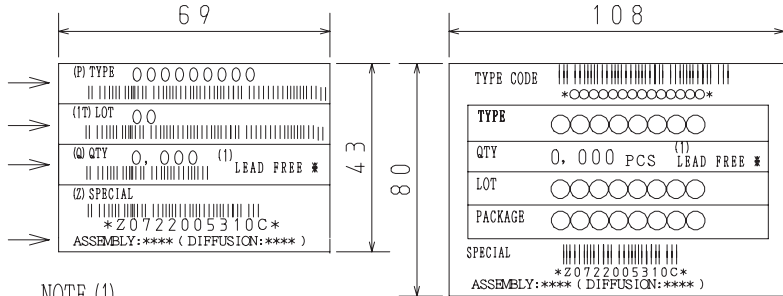
It is a label at the time of factory shipments.
The form of a label may change in physical distribution process.

Packing method



Type No.
LOT No.
Quantity
Origin

Reel label



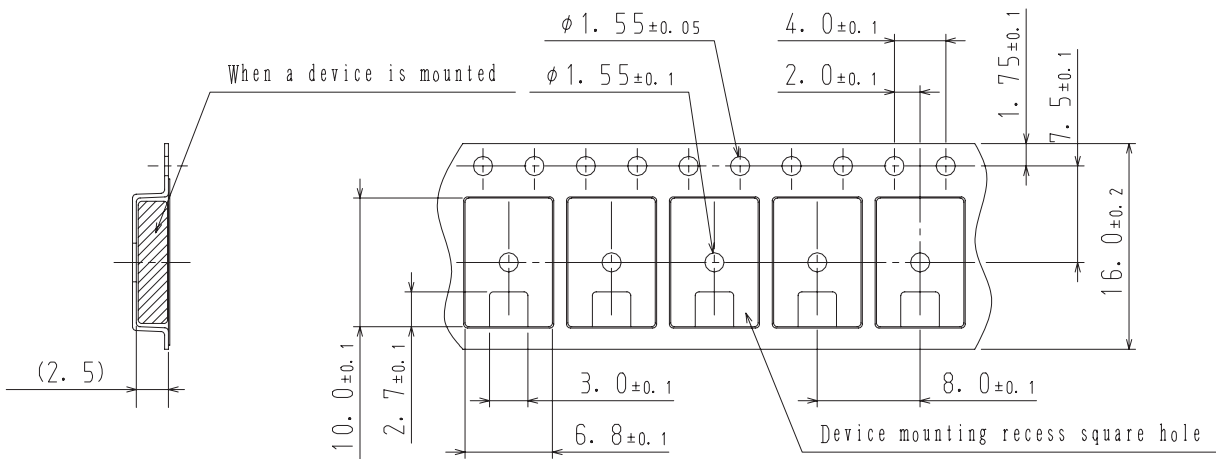
NOTE (1)

The LEAD FREE * description shows that the surface treatment of the terminal is lead free.

Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3

Taping configuration

1. Carrier tape size (unit:mm)



2. Device placement direction

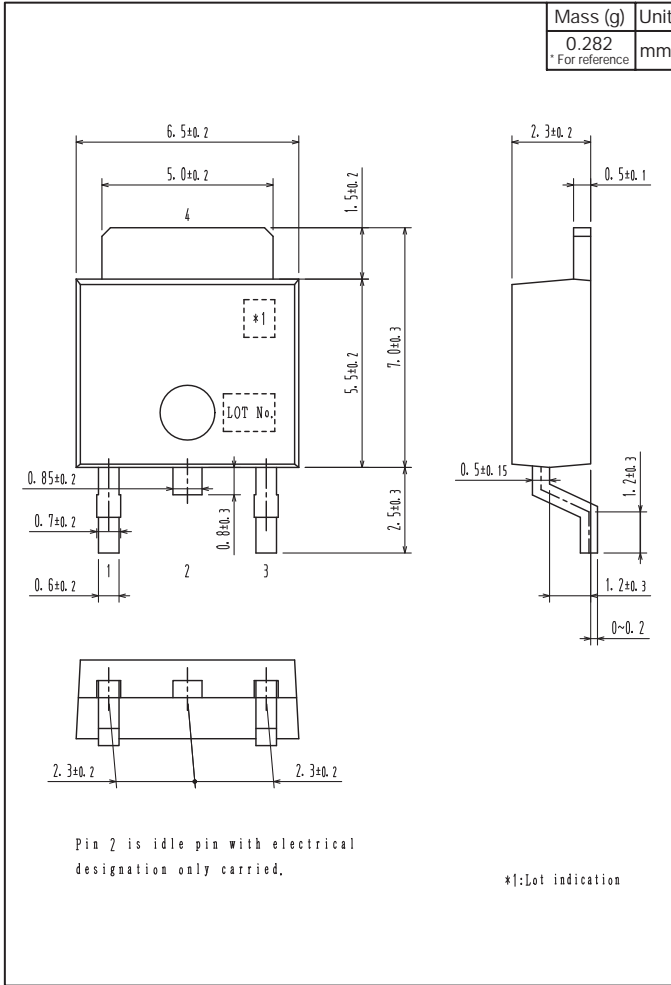


Those with one electrode terminal on the feed hole side.....TL

2SA2040/2SC5707

Outline Drawing

2SA2040-TL-E, 2SC5707-TL-E



Land Pattern Example



Bag Packing Specification

2SA2040-E, 2SC5707-E

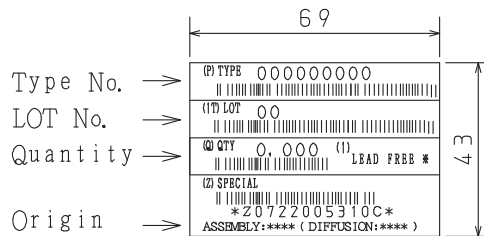
1. Packing Format

Package Name	Maximum Number of devices contained (pcs)			
	Bag	Inner box	Outer box	
TP	500	B-1	A-1	A-2
		10,000	50,000	30,000
	Packing format (Dimensions:mm (external))			
		Inner box	Outer box	
		B-1	A-1	A-2
		445×225×55	470×250×300	470×250×190

2. Bag dimensions
(unit:mm)



3. Bag label, Inner box label
(unit:mm)



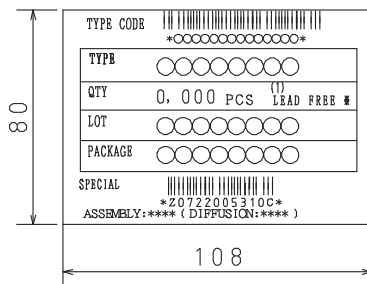
4. Outer box label
(unit:mm)

It is a label at the time of factory shipments.
 The form of a label may change in physical
 distribution process.

NOTE (1)

The LEAD FREE * description shows that the
 surface treatment of the terminal is lead free.

Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3



Outline Drawing

2SA2040-E, 2SC5707-E



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